

COWIN support to SME for exploitation of FP6 and FP7 research projects

The companies supported by COWIN benefit from a unique service to support their growth in combining Yole Finance expertise in business development, corporate strategy and access to finance with EURIPIDES² core positioning in the smart system industry providing access to resources for attractive strategic collaborations.

More than 20 companies have benefited from COWIN support, 12 of them have been presented to private investors who highlighted the real added-value and uniqueness of COWIN support and actions.

COWIN is working in close collaborations with the companies we are supporting. Here are some fresh news that we can share on some of them:



PERCIPIO ROBOTICS

Percipio Robotics enhances extreme robotic micromanipulation for high technology applications

Percipio Robotics a start-up founded in 2011 in Besançon (France) Active in cobotic, brings extreme robotic micromanipulation to perform mass production of assembled miniaturized products in high technology applications.

Percipio Robotics is already working with many customers on robot design, assembly subcontracting, micro device fabrication.

NEWS:

Percipio recently signed a contract with the Heriot Watt University in Scotland to deliver a Micro assembly robotic machine. This equipment will integrate the Chronogrip proprietary technology from Percipio Robotics perfectly suited for Microsystems Packaging providing high accuracy and enhanced robotic capability. This equipment will be delivered for the second half of 2014 and will be installed in the Edinburgh Robotarium . ROBOTARIUM is a new cutting edge facility, a partnership between Heriot-Watt University and the University of Edinburgh and incorporates 50 world-leading investigators from 16 cross disciplinary research groups plus 30 industrial partners including Percipio.

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Multiphoton Optics

Multiphoton Optics demonstrates new ways for Photonics packaging

Multiphoton Optics, a newly founded start-up out of the Fraunhofer Institute for Silicate Research (ISC), received a warm welcome in the Photonics Packaging community at the SPIE Photonics West Conference and Exhibition 2014 in San Francisco. In a joint presentation with the Karlsruhe Institute of Technology and the Fraunhofer ISC, recent results of 3D optical waveguide developments were presented which are pointing towards new opportunities for high-volume manufacturing of photonic packages. [abstract number 8991-5].

NEWS:

Multiphoton Optics has developed a process that allows automation of high-precision optoelectronics assembly of Silicon Photonics chips, III/V Photonic chips or VCSELs, and other components, in optical component packages. The newly available 3D lithography process connects components by Photonic Interconnects with the required precision and repeatability. The Photonic interconnects are created in-situ, and are ideally aligned to the exact location of the components. The process requires 70% less process steps than conventional 2D processes. The technology allows scaling optical packaging operations to very large volume manufacturing. The process is compatible with standard assembly processes known from electronics manufacturing, and can be adapted to customer requirements.

Multiphoton Optics is currently providing Photonics Manufacturing Services (PMS) for demonstration and small volume production to first customers.

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frecn|sys develops frequency components and systems for harsh environment

frecn|sys S.A.S.U., a start-up founded in 2013 in Besançon (France) is providing unique know how in sensors and systems dedicated to harsh environment. frecn|sys solutions aim at targeting a broad range of industrial markets: Aerospace, Defense, Energy Plant Control and Telecommunication.

frecn|sys has already established business partnerships with industrial players, among them: Sensor, Ecologicsense, AR Electronique, GVR Trade, Crystal Innov etc.

NEWS:

The company continues to grow in attracting new customers and signing new contracts with leading companies like EPCOS and other strategic partners.

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